

**N-Ch MOSFET** 

# **General Description**

The WSF3085 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF3085meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

# **Product Summery**

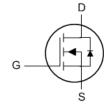
BVDSS	RDSON	ID
30V	4.5mΩ	85A

## **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

	Rating			
Symbol	Parameter	10s	Steady State	Units
V <sub>DS</sub>	Drain-Source Voltage		30	V
$V_{GS}$	Gate-Source Voltage	=	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		85	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		57	Α
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	27	17	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	23	14.5	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> 160		Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup> 252		mJ	
I <sub>AS</sub>	Avalanche Current 48		Α	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>		53	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation⁴	6	2.0	W
T <sub>STG</sub>	Storage Temperature Range	-55	-55 to 175	
TJ	Operating Junction Temperature Range	-55	-55 to 175	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>		62	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤10s)		25	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		2.8	°C/W

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# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =1mA		0.028		V/°C
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		4.5	5.5	
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.8	9	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	)/ -\/   -250\	1.0	1.5	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-6.16		mV/℃
	Drain Source Leakage Current	$V_{DS}$ =24 $V$ , $V_{GS}$ =0 $V$ , $T_J$ =25 $^{\circ}{\rm C}$			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		43		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7	3.1	Ω
$Q_g$	Total Gate Charge (4.5V)			20	28	
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.6	10.6	nC
$Q_{gd}$	Gate-Drain Charge			7.2	10.1	
T <sub>d(on)</sub>	Turn-On Delay Time			11	15.6	
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		15	27	20
T <sub>d(off)</sub>	Turn-Off Delay Time			37.3	74.6	ns
T <sub>f</sub>	Fall Time			10.6	21.2	
Ciss	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		2295	3213	
C <sub>oss</sub>	Output Capacitance			570	374	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			210	294	

## **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =24A	63			mJ

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			35	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				160	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1	V
t <sub>rr</sub>	Reverse Recovery Time			30		nS
Q <sub>rr</sub>	Reverse Recovery Charge	IF=30A , dI/dt=100A/ $\mu s$ , T $_{J}$ =25 $^{\circ} \! \mathbb{C}$		24		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =24A
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



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# **Typical Characteristics**

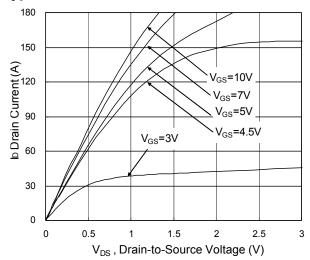


Fig.1 Typical Output Characteristics

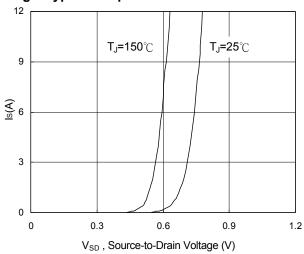


Fig.3 Forward Characteristics of Reverse

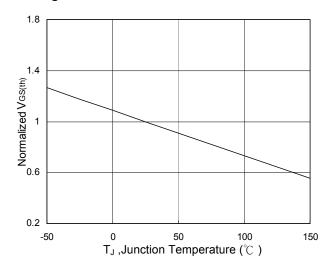


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

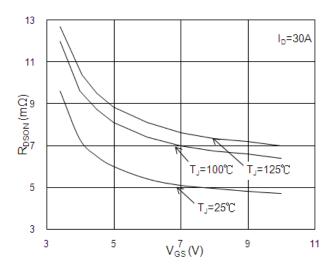


Fig.2 On-Resistance vs. G-S Voltage

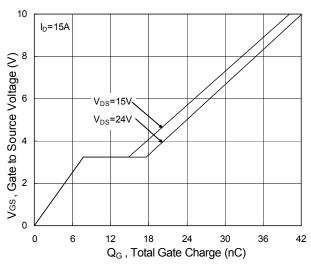


Fig.4 Gate-Charge Characteristics

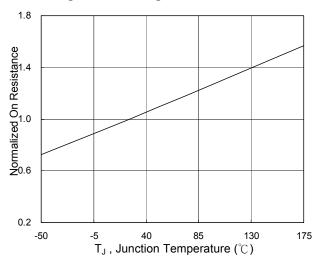
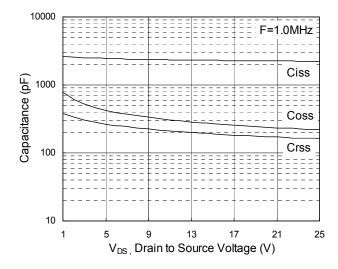


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>







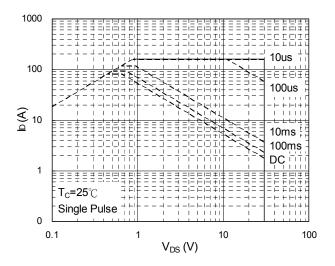


Fig.7 Capacitance

Fig.8 Safe Operating Area

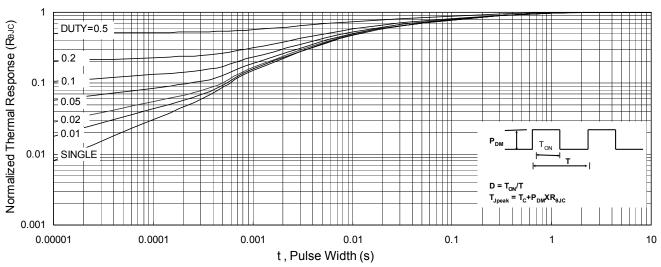


Fig.9 Normalized Maximum Transient Thermal Impedance

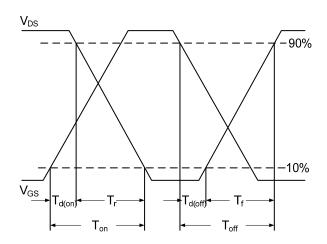


Fig.10 Switching Time Waveform

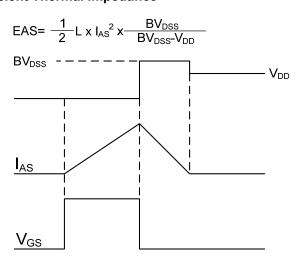


Fig.11 Unclamped Inductive Switching Waveform



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